/ Descriptions

TO-92(R) NPN Silicon NPN transistor in a TO-92(R) Plastic Package.

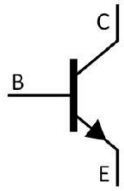
/ Features

High Voltage, Low Noise.

/ Applications

Low noise amplifier application.

/ Equivalent Circuit



/ Pinning



PIN1 Emitter PIN 2 Base PIN 3 Collector

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	A	B	C
h_{FE} Range	110 220	200 450	420 800

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	45	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	100	mA
Collector Power Dissipation	P_C	625	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

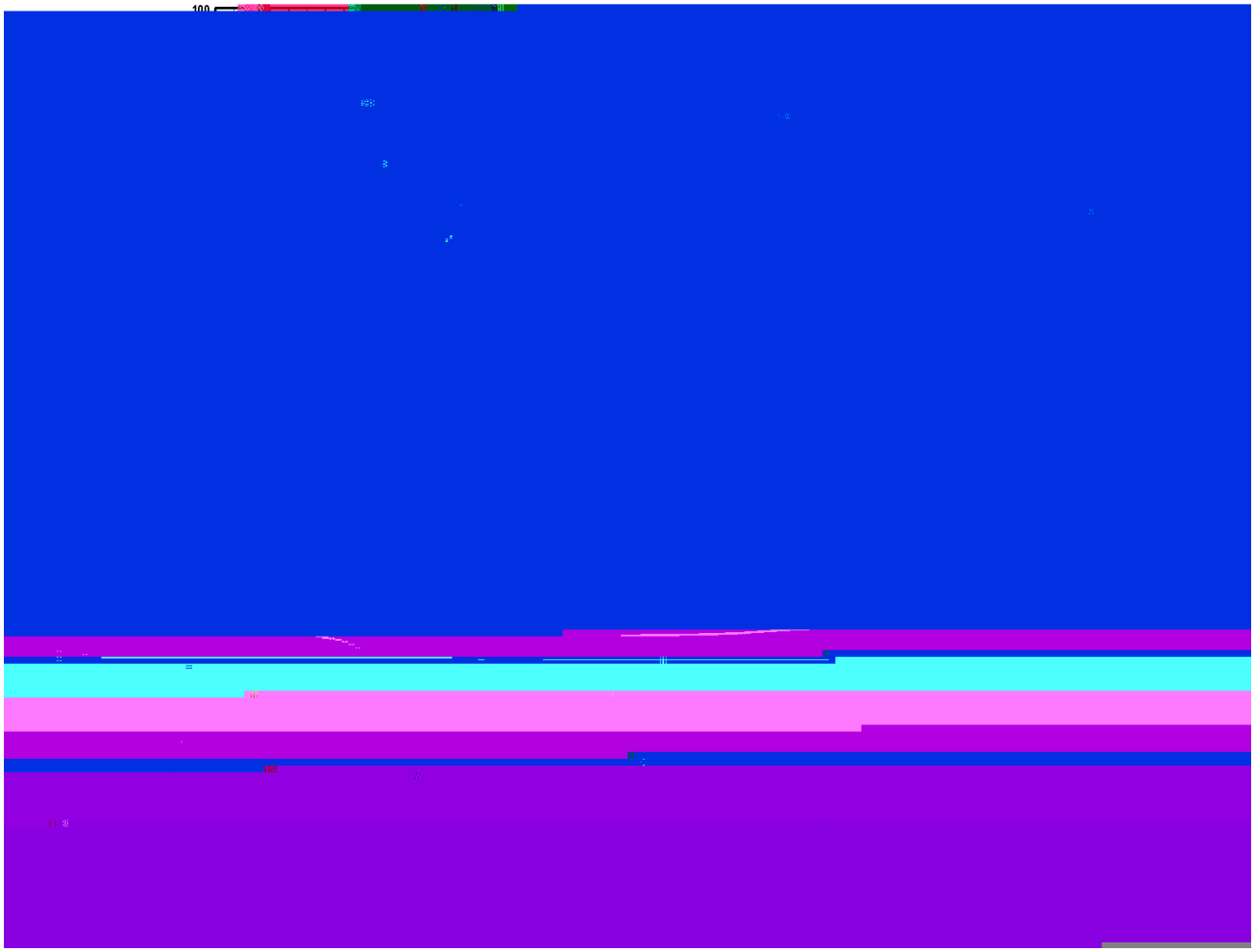
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown						

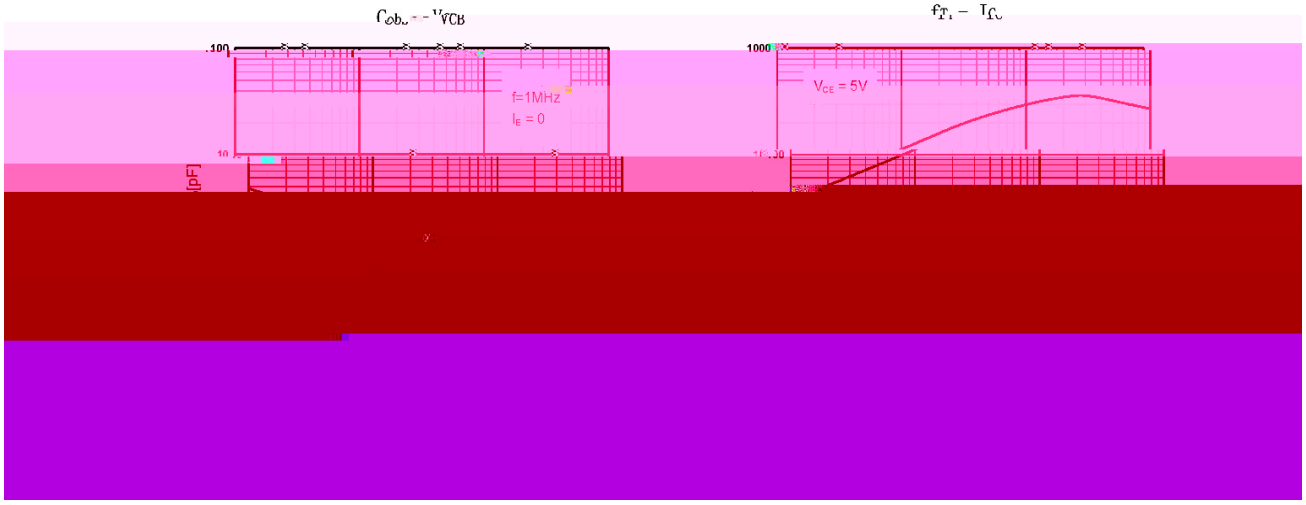
/ Electrical Characteristic Curve

$I_C - V_{CE}$

$I_C - V_{BE}$

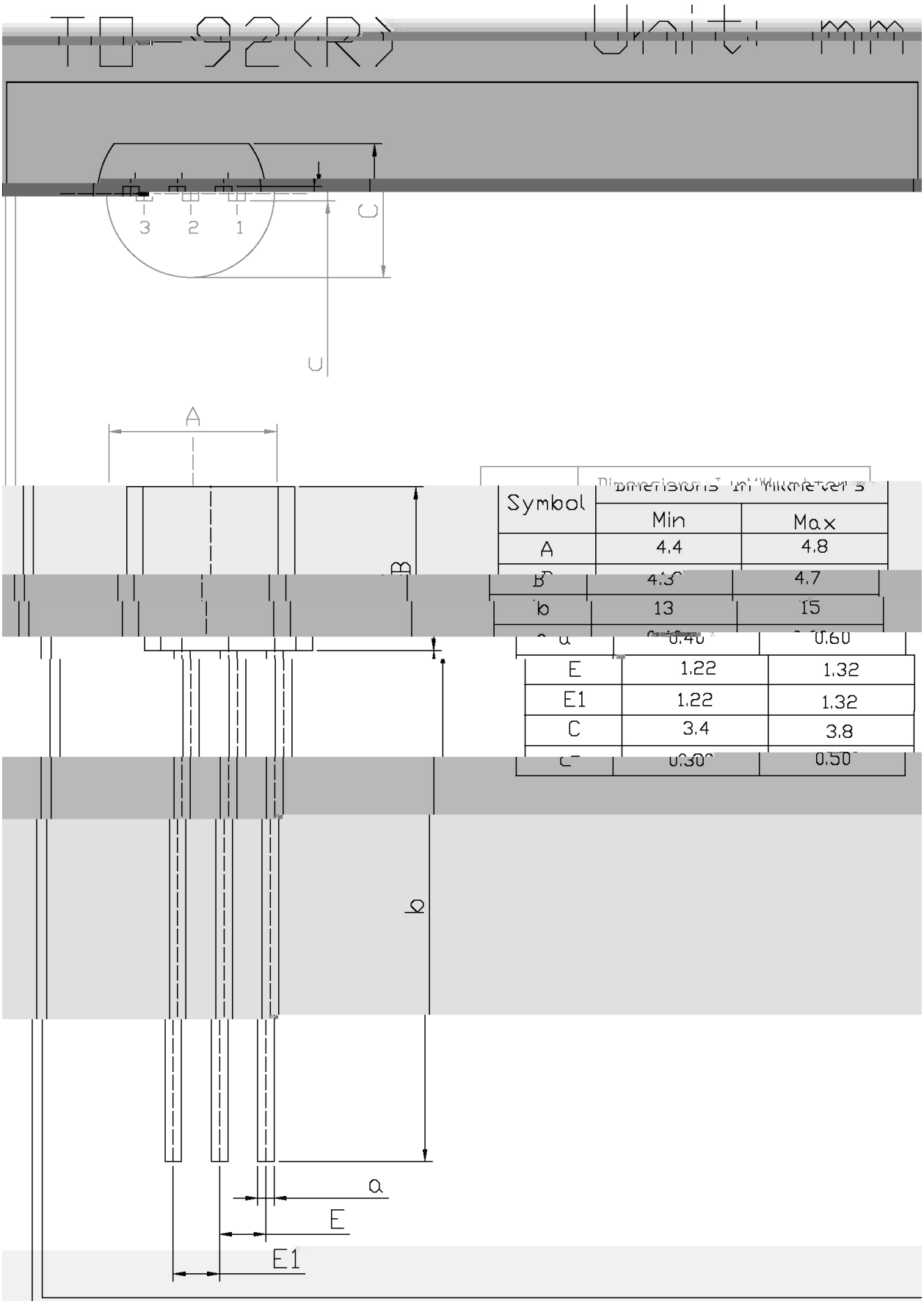


$C_{ob} - V_{CB}$



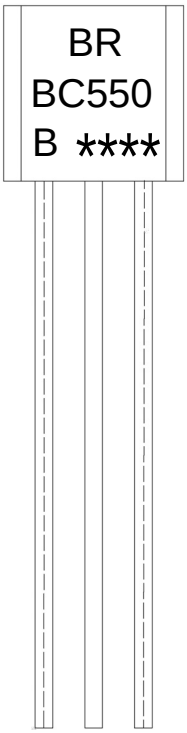
$f_T - I_C$

/ Package Dimensions



Symbol	Dimensions In Millimeters	
	Min	Max
A	4.4	4.8
B	4.3	4.7
b	13	15
a	0.40	0.60
E	1.22	1.32
E1	1.22	1.32
C	3.4	3.8
c	0.30	0.50

/ Marking Instructions



BR

BC550

B h_{FE}

****

Note:

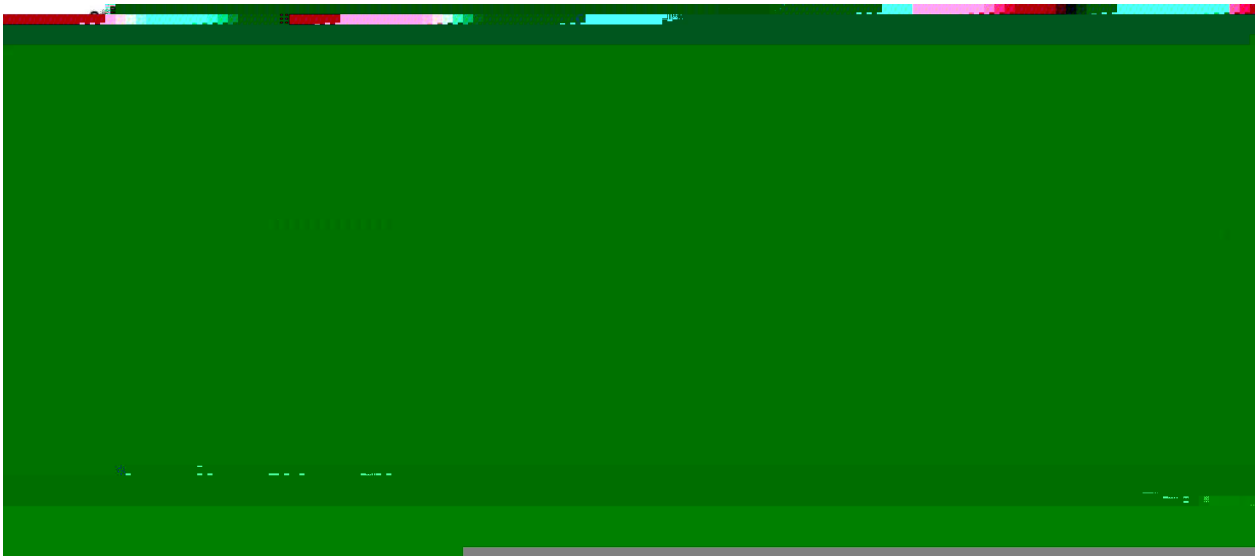
BR: Company Code.

BC550: Product Type.

B h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



					Note:
1	25	150	60	90sec;	1.Preheating:25~150 , Time:60~90sec.
2	255±5			5±0.5sec;	2.Peak Temp.:255±5 , Duration:5±0.5sec.
3		2	10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

270±5	10±1 sec.	Temp.:270±5	Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension	(unit mm3)
	Units/Bag	Bags/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box		
T5w67-60	1000	1	338	1	338	Bag0	1000